



[10191/3964]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Franz LAERMER et al.
Serial No. : 10/530,612
Filed : December 30, 2005
For : **PLASMA SYSTEM AND METHOD FOR
ANISOTROPICALLY ETCHING STRUCTURES
INTO A SUBSTRATE**

Art Unit : 1792
Examiner : Maki A. Angadi
Confirmation No. : 6739

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on:

Date: September 14, 2009

Signature: 
Richard M. Rosati (Reg. No. 31,792)

RESPONSE

SIR:

In response to a July 2, 2009 Office Action in the above-identified application, please reconsider the above-captioned application as follows.

Remarks begin on page 2 of this paper.